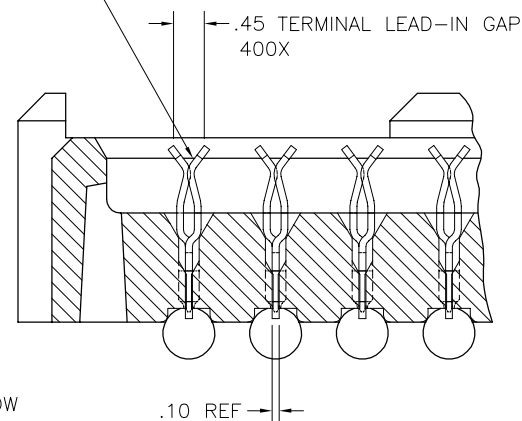
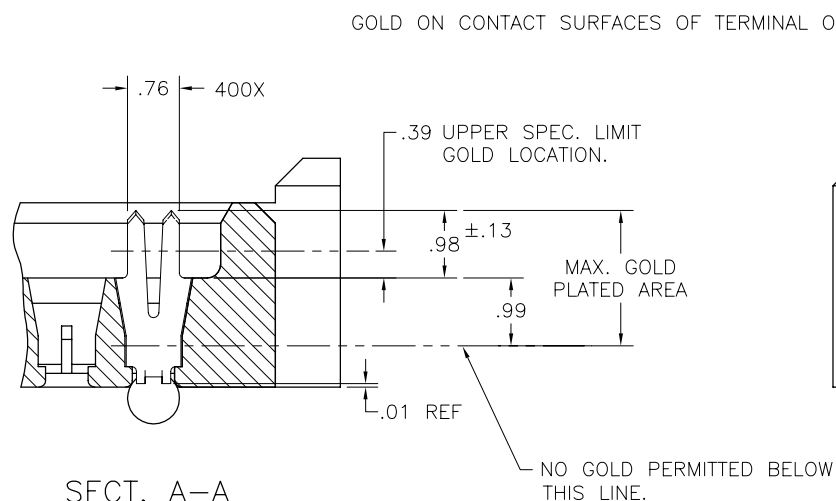


Printed: Dec 10, 2008

**NOTES:****1. MAT'L:**

HOUSING: LCP (GRADE PROPRIETARY).

CONTACT: BeCu/C17200.

PLATING:

CONTACT: 15-40u"/.38-1.02um Au OVER 30-120u"/.76-3.05um Ni.

SOLDER BALL: (SEE TABLE ON SHEET1)

EUTECTIC SnPb OR LEAD FREE

95.5Sn/4Ag/0.5Cu

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT. NOMINAL INITIAL SOLDER BALL ϕ .76 (.030").
3. DRAWING NO. 74221 TO BE USED FOR INTEL CUSTOMERS (OEM).
4. REFER TO 07-747 INTEL PROCUREMENT SPEC.
5. SOLDER BALL HEIGHT TOLERANCE PENDING FINAL AGREEMENT.

6. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

CONFIDENTIAL: INTEL INTERNAL USE ONLY SEE NOTE 3.

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection 	product family MEG-ARRAY			
ltr	ecr no	dr	date	tolerances unless otherwise specified			title			
g				angles	line fit	X *3	4mm RECPT ASSY			
				0° ±2°		XX *13	10X40= 400 POS.			
				dr	M.J.WENDEL	971013	scale 10:1			
				enr	T.LEMKE	10.14.97				
				chr	T.LEMKE	10.14.97				
				appd	T.LEMKE	10.14.97	dwg no			
sheet	revision						sheet 3 of 3			
index	sheet						74220			
							type			
							CUSTOMER Drawing			